


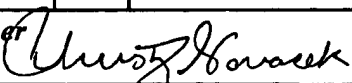
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US Department of Commerce Patent and Trademark Office Form PTO-1449 (Modified)		Atty. Docket No.: 42390P9978C		Application No.: Not Yet Assigned		
		Applicant: Maeda et al.				
		Filing Date: Concurrently Herewith				
US Patent Documents						
Examiner's Initials	Date	Document Number	Name	Class	Sub-Class	Filing Date
CX	05/28/91	5,019,673	Juskey et al.			08/22/90
CX	05/05/92	5,111,279	Pasch et al.			08/30/90
CX	09/22/92	5,150,274	Okada et al.			07/09/91
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CX	04/16/96	5,508,561	Tago et al.			11/14/94
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CX	07/14/98	5,778,913	Degani et al.			02/20/97
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Foreign Patent Documents						
Examiner's Initials	Date	Document Number	Country	Class	Sub-Class	Translation
CX	06/23/88	JP63151033	Japan			
Other Documents (Including Author, Title, Date, Pertinent Pages, etc.)						
Examiner's <i>Christy Horvack</i>			Date Considered 11/9/05			

Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw a line through the citation if not in conformance and not considered. Include a copy of this form with the next communication to the applicant

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US Patent Documents						
Examiner's Initials	Date	Document Number	Name	Class	Sub- Class	Filing Date
OX	01/06/98	5,704,116	Gamota et al.			
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OX	05/02/00	6,057,168	Seyama et al.			
OX	01/11/00	6,013,572	Hur et al.			
OX	06/04/02	6,400,034	Kimura et al.			
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OX	09/01/88	63-004652	Japan			Y
OX	08/29/88	63-208251	Japan			Y
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OX		Pooya Tadayon, Sort Test Technology Development, Intel Corporation. "Thermal Challenges Diring Microprocessor Testing". Intel Technology Journal Q3, 2000. Pgs. 1-8.				
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Examiner 			Date Considered 11/9/05			

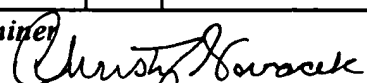
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OK		07/28/98	5,785,234	Weiss et al.			
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OK	12/24/91	5,074,920	Gonsiorawski et al.			
Foreign Patent Documents						
Examiner's Initials	Date	Document Number	Country	Class	Sub-Class	Translation
Other Documents (Including Author, Title, Date, Pertinent Pages, etc.)						
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Examiner Christy Horacek			Date Considered 11/9/05			

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US Patent Documents							
Examiner's Initials		Date	Document Number	Name	Class	Sub- Class	Filing Date
CK		05/09/00	6,059,894	Pendse			
Foreign Patent Documents							
Examiner's Initials		Date	Document Number	Country	Class	Sub- Class	Translation
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CK		Ravi Mahajan, Ken Brown & Vasu Atluri. "The Evolution of Microprocessor Packaging". Intel Technology Journal Q3, 2000. Pgs. 1-10.					
CK		Greig, W.J. "A Review of ThermoCompression Flip Chips Assembly", Electronic Packaging and Production, Pages 70-74, XP000776056.					
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Examiner 				Date Considered 11/9/05			

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Based on PTO/SE/08B (08-03) as modified by Blakely, Solokoff, Taylor & Zafman (wtr) 08/11/2003.
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